

dfRev 02/07

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application : Satoshi Murouchi, et al.
 Application No.: 10/519,046
 Filed : August 19, 2005
 Confirmation No. : 6619
 For : WHOLLY AROMATIC LIQUID CRYSTAL...
 Examiner : Michael B. Nelson
 Attorney's Docket : AK-481XX

TC Art Unit: 1794

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Declaration of Yoshiharu Iwasaki

Via EFS-Web
 Commissioner for Patents
 P.O. Box 1450
 Alexandria, VA 22313-1450

Sir:

I, Yoshiharu Iwasaki, declare as follows:

1) I am currently Deputy General Manager of the Advanced Polymers Department of the Chemicals Division of Nippon Oil Corporation. My responsibilities have included the management of the LCP business of Nippon Oil Corporation since April of 2005. I also worked on production process development of polyethylene for 2 years, catalyst development for polypropylene for 3 years, and research and development for resin materials for automobiles for 7 years. My work has also included research and development for the injection molding of resin materials for 4 years and the

development of LCP for 5 years. I am named as inventor on numerous granted patents, including 12 Japanese patents (e.g., JP 1,933,949, 2,050,588, and 3,506,539), 4 European patents (EP 267,794, 471,078, 466,930, and 465,664), and 4 U.S. patents (U.S. 5,266,362, 5,190,704, 5,200,122, and 5,240,973).

2) I am familiar with U.S. Patent Application Ser. No. 10/519,046, and I have read the application and examined the drawings for the application. I understand that this application claims priority to Japanese Patent Application No. 2002-185354 filed June 25, 2002.

3) It is known to a person of skill in the art of polymer resins that a mathematical relationship exists between the dielectric constant for a resin composition and the dielectric constants of the components of the composition. That mathematical relationship is the following:

$$\log \varepsilon = X_1 \log \varepsilon_1 + X_2 \log \varepsilon_2$$

In other words, the ordinary skilled artisan at the priority date of the 10/519,046 application would have expected that the

logarithm of the dielectric constant of a product made by molding an organic resin composition is represented by the sum of the product of the volume fraction of each component and the logarithm of the dielectric constant for each component. This relationship is described on page 283 of "Theory of Solid Dielectrics" published in 1960 by Syoten OKA (Japanese version with English translation attached as Exhibit A). Specifically, ϵ represents the dielectric constant of the composition; ϵ_1 , ϵ_2 , etc., represent the dielectric constants of each of the components; and X_1 , X_2 , etc., represent the volume fractions of each of the components. This equation is thought to also apply for a resin composition comprising a liquid crystal polymer (hereinafter "LCP") and inorganic fillers, including inorganic spherical hollow material such as glass balloons (hereinafter "GB").

4) According to the above relation, the logarithm of the dielectric constant for a resin composition comprising LCP and inorganic spherical hollow material such as GB is the sum of the product of the volume fraction and the logarithm of the dielectric constant for each of the components (namely LCP, GB, and glass (fractured GB)). Therefore, it can be expected that the logarithm of the dielectric constant for the mixed resin composition (and

also the dielectric constant itself) increases monotonically as the fracture rate of hollow material (i.e., GB) increases. Qualitatively, this can be understood as the steadily decreasing contribution of air, in the form of intact GB, as the GB fracture rate increases.

5) Thus, the ordinary skilled person at the priority date of the 10/519,046 application would have understood and expected that the dielectric constant for an LCP resin composition containing GB would monotonically increase as the fracture rate of GB increases.

6) Such an ordinary skilled person also would have expected that the dielectric constant for a molded product obtained by injection molding an LCP resin composition containing GB increases continuously over the range of fracture rate of 0.045 to 0.094, as recited in claim 1 of the 10/519,046 application.

7) I have reviewed Graph 1 that was submitted with the Applicant's response to USPTO on January 14, 2009 by the Applicant. Graph-1 shows a distribution of data in which no points are represented in the range of fracture rates from 0.05 to 0.08.

However, the ordinary skilled person would have expected a continuous increase of dielectric constant over the range of fracture rates from 0.05 to 0.08, even though that range is not populated with data points. This is because, as explained in paragraphs 3) through 6) above, the ordinary skilled person would have expected the dielectric constant for an LCP resin composition containing GB to increase continuously as the fracture rate of GB increases, even if there had been no points between the endpoints of 0.045 and 0.094. From my professional point of view, it cannot be expected that the dielectric constant of a molded product obtained from an LCP resin composition comprising GB and having a fracture rate as recited in claim 1 of the 10/519,046 application would depart drastically from the relationship shown in Graph 1 and exceed a value of 3.0. There is no basis to expect such a result.

8) In conclusion, the ordinary skilled person at the priority date of the 10/519,046 application would have readily assumed that the dielectric constant of a molded product obtained by injection molding an LCP resin composition comprising the amount of inorganic spherical hollow material recited in claim 1 of the 10/519,046 application would be less than 3.0 over the

entire range of fracture rate of the inorganic spherical hollow material of 0.045 to 0.094, even though this is not verified in the Examples over some portion the range. One of ordinary skill in the art would have appreciated that the inventors were in possession a molded product having a dielectric constant of 3.0 or less and a dielectric dissipation factor of 0.04 or less even at fracture rates in the middle section of the claimed range of fracture rates (e.g. 0.05-0.08).

I hereby declare that all statements made herein on personal knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

Signed this 18 day of September, 2009.


Yoshiharu Iwasaki

383650.1

Translation of "Theory of Solid Dielectrics" issued in 1960, Syoten Oka, Osamu Nakata, relevant part on page 283

§89 Dielectric constant of a mixture

Logarithmic relational expression is mostly approved for a mixture of rutile powder and other ceramics and/or organic resins and/or liquids.

$$\log \epsilon = X_1 \log \epsilon_1 + X_2 \log \epsilon_2$$

wherein ϵ_1 , ϵ_2 : dielectric constant of each component and X_1 , X_2 : volume fraction thereof.

Generally it is very convenient if a dielectric constant of a mixed substance is calculated from components' dielectric constant or if other component's dielectric constant can be calculated knowing a dielectric constant of mixed substance and a dielectric constant of one component. Not limiting with a dielectric constant, these kinds of subjects for various kind of physical property values have been studied since long time among physicists.

固体誘電体論

小田 天修 著
岡 中

岩波書店

